

# BAS70JW

#### SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAY

#### **Features**

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- Lead Free/RoHS Compliant (Note 3)

#### **Mechanical Data**

Case: SOT-363

 Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0

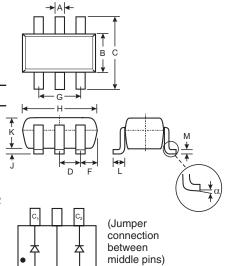
Moisture Sensitivity: Level 1 per J-STD-020C

Terminals: Solderable per MIL-STD-202, Method 208

 Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe). Please see Ordering Information, Note 5, on Page 3

Orientation: See DiagramMarking: K78 (See Page 3)

Weight: 0.006 grams (approximate)



	SOT-363									
Dim	Min	Max								
Α	0.10	0.30								
В	1.15	1.35								
С	2.00	2.20								
D	0.65 Nominal									
F	0.30 0.40									
Н	1.80 2.20									
J	— 0.10									
K	0.90 1.00									
L	L 0.25									
М	0.10	0.25								
α	0°	8°								
All Dimensions in mm										

## Maximum Ratings @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit		
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	70	V		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	49	V		
Forward Continuous Current (Note 1)	I <sub>FM</sub>	70	mA		
Non-Repetitive Peak Forward Surge Current @ t < 1.0s	I <sub>FSM</sub>	100	mA		
Power Dissipation (Note 1)	Pd	200	mW		
Thermal Resistance Junction to Ambient Air (Note 1)	$R_{ hetaJA}$	625	°C/W		
Operating and Storage Temperature Range	T <sub>j</sub> T <sub>STG</sub>	-55 to +125 -65 to +125	°C		

TOP VIEW

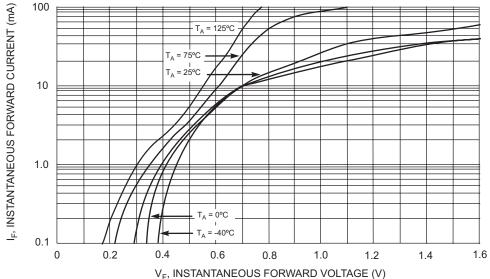
#### **Electrical Characteristics** @ T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V <sub>(BR)R</sub>	70	_	V	$I_R = 10\mu A$
Forward Voltage	V <sub>F</sub>	_	410 1000	mV mV	$t_p < 300 \mu s, I_F = 1.0 mA$ $t_p < 300 \mu s, I_F = 15 mA$
Reverse Current (Note 2)	I <sub>R</sub>	_	100	nA	$t_p < 300 \mu s, V_R = 50 V$
Total Capacitance	C <sub>T</sub>	_	2.0	pF	V <sub>R</sub> = 0V, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	_	5.0	ns	$I_F = I_R = 10$ mA to $I_R = 1.0$ mA, $I_{T} = 0.1 \times I_R$ , $R_L = 100\Omega$

Notes: 1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

- 2. Short duration test pulse used to minimize self-heating effect.
- 3. No purposefully added lead.







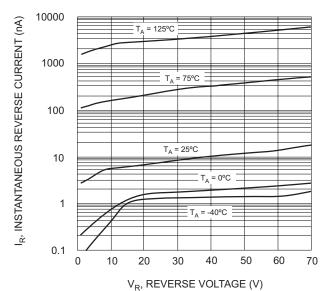


Fig. 2 Typical Reverse Characteristics

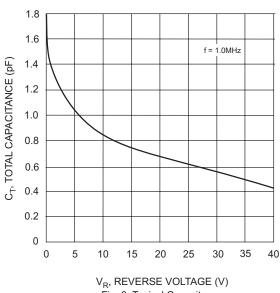


Fig. 3 Typical Capacitance

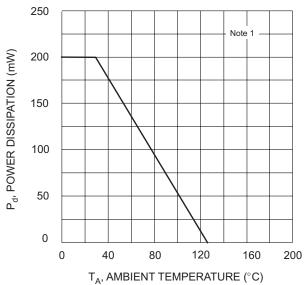


Fig. 4 Power Derating Curve, Total Package



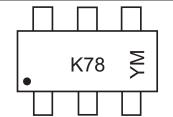
#### Ordering Information (Note 4)

Device	Packaging	Shipping			
BAS70JW-7-F	SOT-363	3000/Tape & Reel			

Notes: 4. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

5. For Lead Free/RoHS Compliant version part number, please add "-F" suffix to the part number above. Example: BAS70JW-7-F.

### **Marking Information**



K78 = Product Type Marking Code YM = Date Code Marking

Y = Year ex: N = 2002 M = Month ex: 9 = September

Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	М	N	Р	R	S	Т	U	V	W	Х	Υ	Z

Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

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